

## TGF30SF

Leader Tech's TGF30SF (silicone free thermal pad) are widely used in high-end electronic industries such as high sensitivity detectors and high-definition camera. Made with an acrylic adhesive, is especially suitable for silicone oil sensitive places and avoids any oil leakage after prolonged use. It provides good insulation, excellent resistance to aging, high flexibility and good self-adhesive.

### **Features:**

- No silicone components
- High thermal conductivity
- Good flexibility
- High strength and elasticity.

### **Applications:**

- Mobile electronic equipments
- Microprocessors and chips
- Automotive engine control units
- Laptop computers
- Wireless communication hardware products

### **Storage Conditions:**

- Store in the darkness
- Storage Temperature:  $\leq 30^{\circ}\text{C}$
- Storage Humidity:  $\leq 70\%$
- When stacking the parts, the parts should not be higher than 7 layers or more than 1mm

### **Shelf Life:**

- Stored at storage conditions: Two years
- Stored in unqualified storage conditions: 6 months

**Properties:**

| Item                  | Parameter   | Unit    | Test Method     |
|-----------------------|-------------|---------|-----------------|
| Color                 | Gray White  | -       | Visual          |
| Specification         | 200*400     | mm      | ASTM D5947      |
| Thickness             | 0.5 ~ 3     | mm      | ASTM D374       |
| Hardness              | 35~50(±5)   | Shore C | ASTM D2240      |
| Density               | 2.9(±0.2)   | g/cc    | ASTM D792       |
| Tensile Strength      | ≥0.15       | Mpa     | ASTM D412       |
| Elongation            | ≥80         | %       | ASTM D412       |
| Tear Strength         | N/A         | N/mm    | ASTM D624       |
| Compression Ratio     | ≥25(@50PSI) | %       | ASTM D695       |
| UL Certification      | V0          | -       | UL94            |
| Operating Temperature | -40 ~ 150   | °C      | IEC 600068-2-14 |

**Thermal Characteristics:**

|                      |                  |                      |            |
|----------------------|------------------|----------------------|------------|
| Thermal Conductivity | 3.0 (±0.25)      | W / m·K              | ASTM D5470 |
| Thermal Resistance   | ≤0.6(@20PSI/1mm) | °Cin <sup>2</sup> /W | ASTM D5470 |

**Electrical Properties:**

|                    |                 |      |           |
|--------------------|-----------------|------|-----------|
| Breakdown Voltage  | ≥8(@1mm)        | KV   | ASTM D149 |
| Volume Resistivity | 10 <sup>8</sup> | Ω·cm | ASTM D257 |

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